

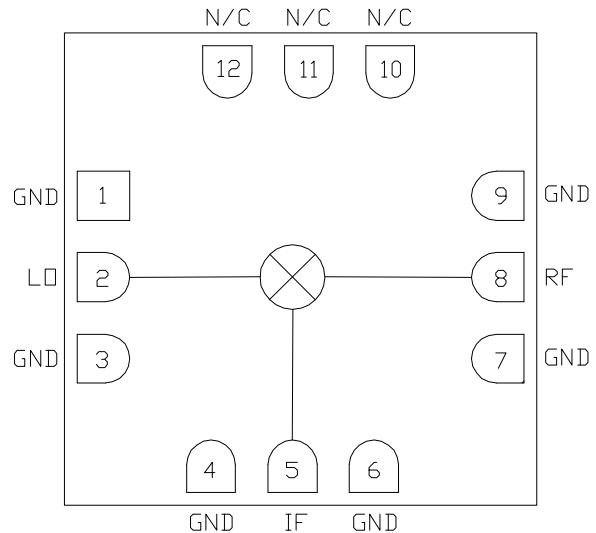
### Features

- ▶ Low conversion loss
- ▶ High isolation
- ▶ Wide IF bandwidth
- ▶ Passive double balanced topology
- ▶ Pb-free RoHs compliant 3x3 mm SMT package

### Description

The CMD177C3 is a general purpose double balanced mixer in a leadless surface mount package that can be used for up- and downconverting applications between 6 and 14 GHz. The CMD177C3 has very high isolation to both the RF and IF ports due to the optimized balun structures, and can operate with an LO drive level as low as +9 dBm. The CMD177C3 can easily be configured as an image reject mixer or single sideband modulator with external hybrids and power splitters.

### Functional Block Diagram



### Electrical Performance - IF = 100 MHz, LO = +13 dBm, T<sub>A</sub> = 25 °C, F = 10 GHz

Parameter	Min	Typ	Max	Units
Frequency Range, RF & LO	6 - 14			GHz
Frequency Range, IF	DC		5	GHz
Conversion Loss		6.5		dB
LO to RF Isolation		43		dB
LO to IF Isolation		37		dB
RF to IF Isolation		22		dB
Input P1dB		9.5		dBm

Unless otherwise noted, all measurements performed as a downconverter, IF = 100 MHz



# CMD177C3

## 6-14 GHz Fundamental Mixer

### Specifications

#### Absolute Maximum Ratings

Parameter	Rating
RF / IF Input Power	+25 dBm
LO Drive	+25 dBm
Operating Temperature	-40 to 85 °C
Storage Temperature	-55 to 150 °C

Operation of this device outside the maximum ratings may cause permanent damage.

#### Electrical Specifications - IF = 100 MHz, LO = +13 dBm, T<sub>A</sub> = 25 °C

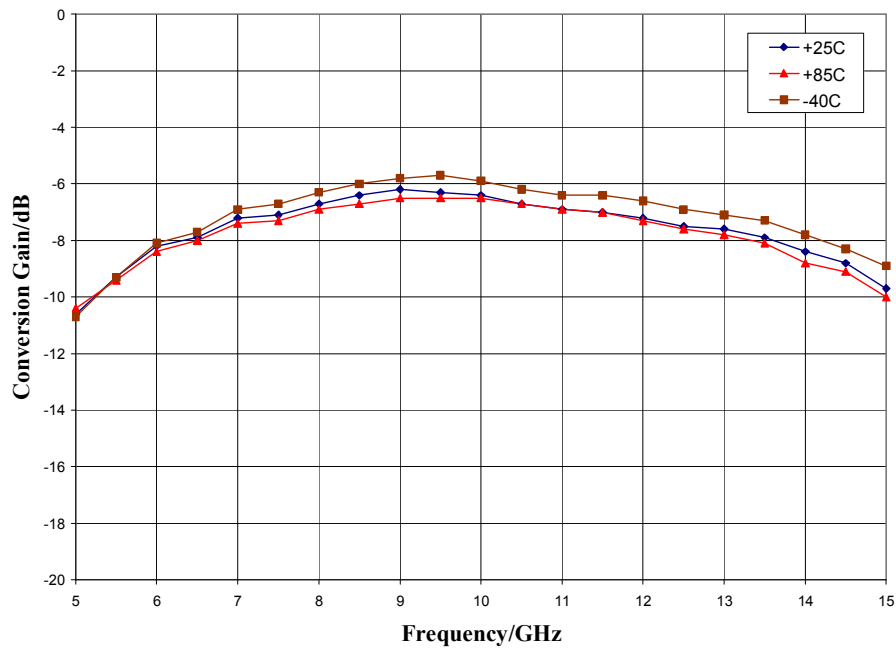
Parameter	Min	Typ	Max	Min	Typ	Max	Units
Frequency Range, RF & LO	8 - 12			6 - 14			GHz
Frequency Range, IF	DC		5	DC		5	GHz
Conversion Loss		6.5	8		7	10	dB
Noise Figure (SSB)		6.5	8		7	10	dB
LO to RF Isolation	37	43		34	43		dB
LO to IF Isolation	28	37		28	37		dB
RF to IF Isolation	15	22		12	22		dB
Input P1dB		9.5			9.5		dBm
Input IP3		16			16		dBm

Unless otherwise noted, all measurements performed as a downconverter, IF = 100 MHz

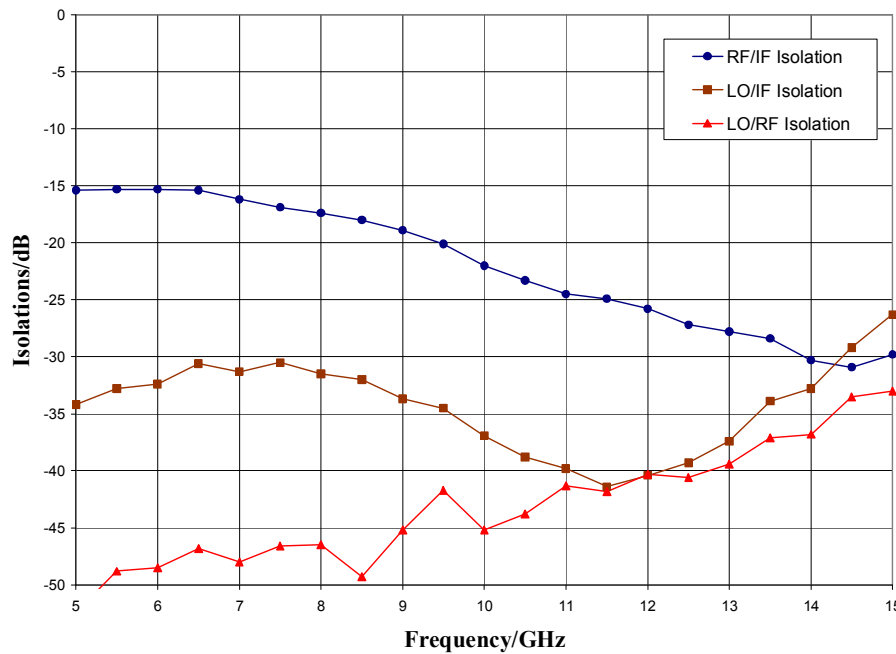
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### Typical Performance

**Conversion Gain vs. Temperature, LO = +13 dBm, IF = 100 MHz USB**



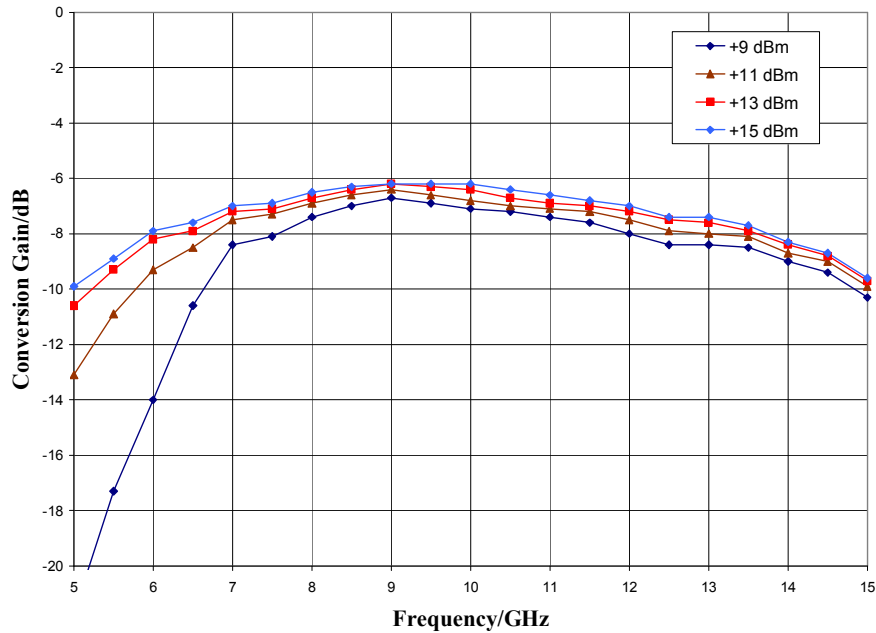
**Isolation, LO = +13 dBm**



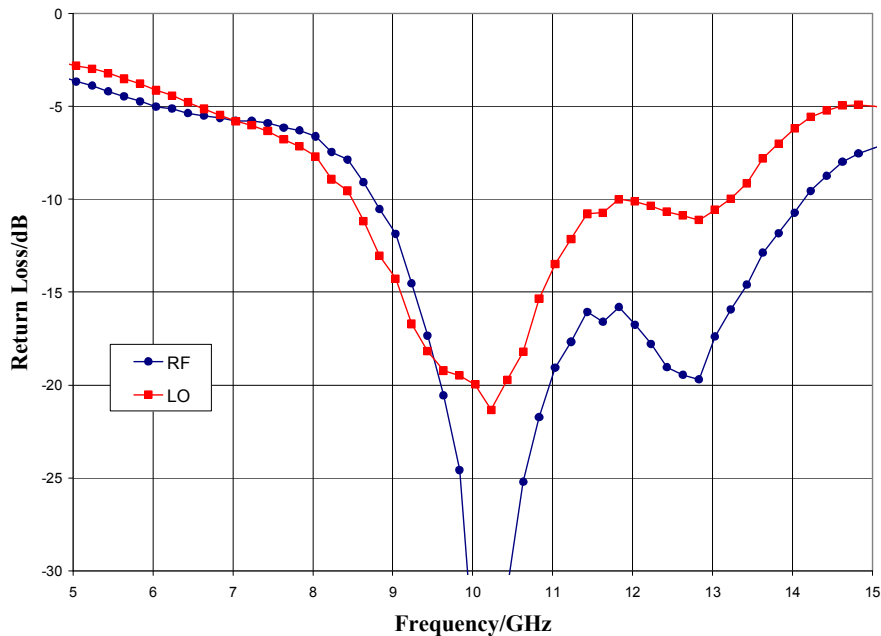
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### Typical Performance

**Conversion Gain vs. LO Drive, IF = 100 MHz USB**



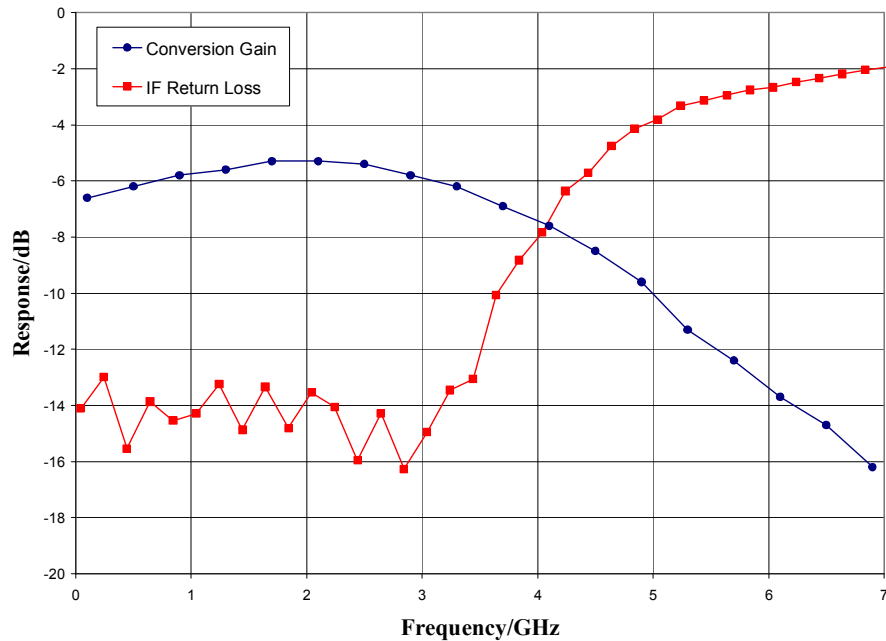
**Return Loss, LO = + 13 dBm**



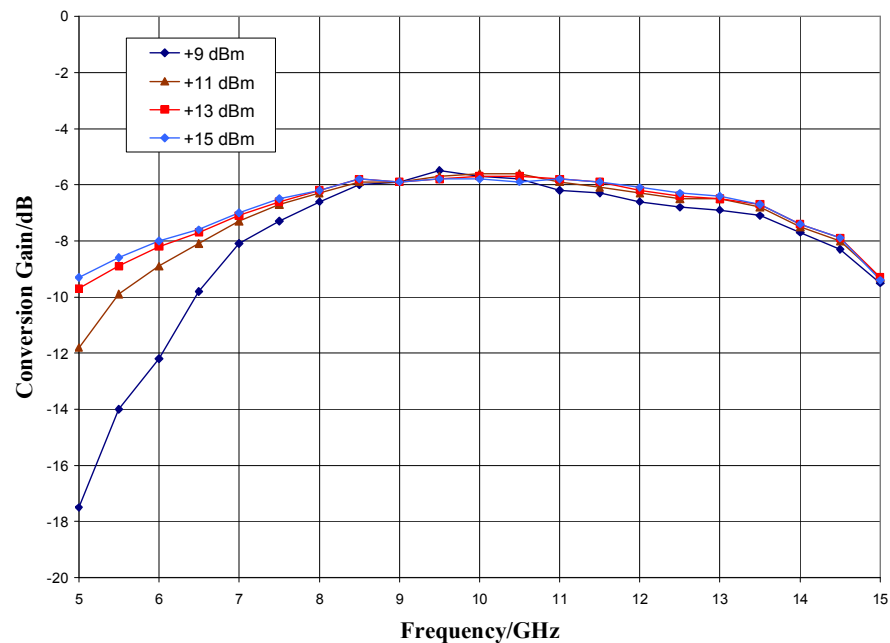
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### Typical Performance

IF Bandwidth, LO = +13 dBm



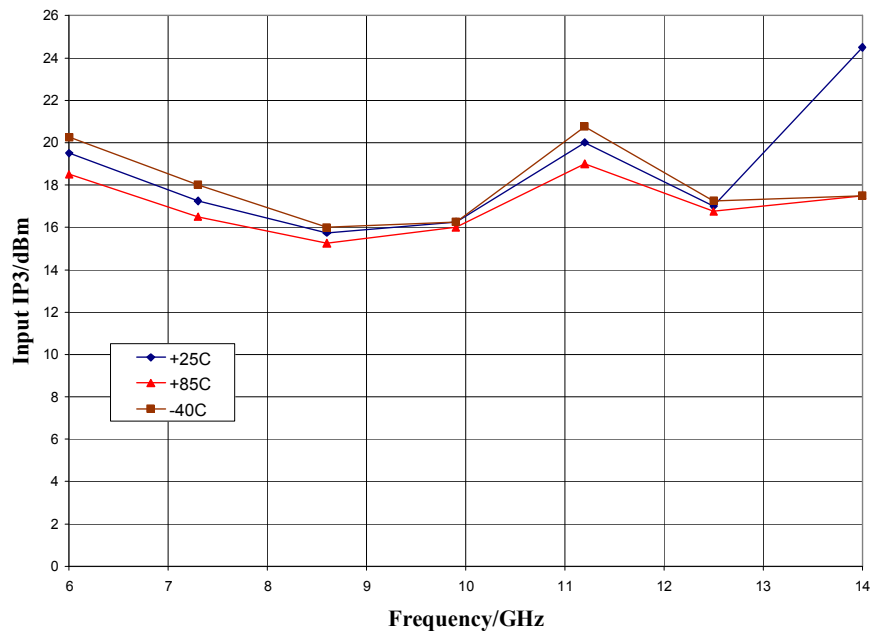
Upconverter Performance, Conversion Gain vs. LO Drive, IF input = 100 MHz



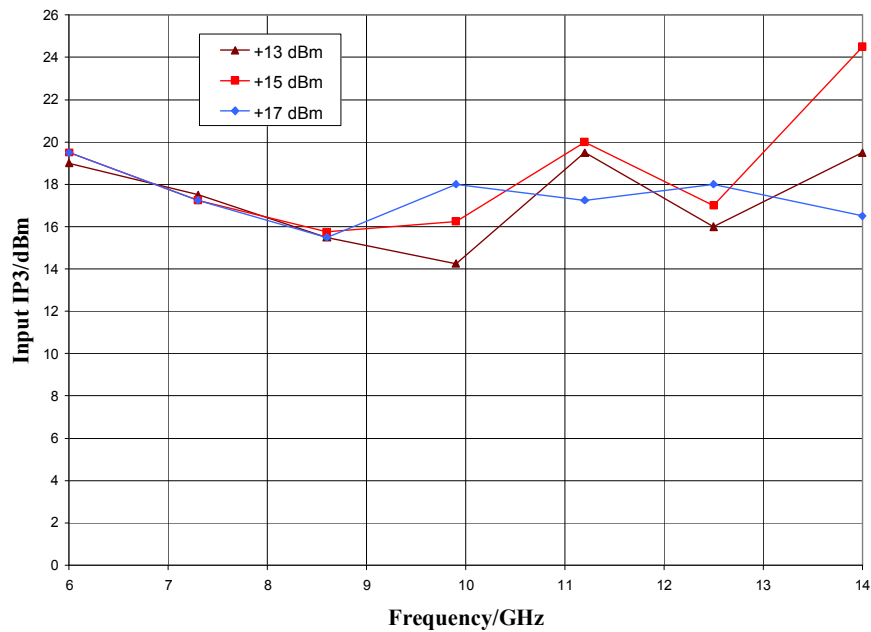
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### Typical Performance

**Input IP3 vs. Temperature, LO = +15 dBm, IF = 100 MHz**



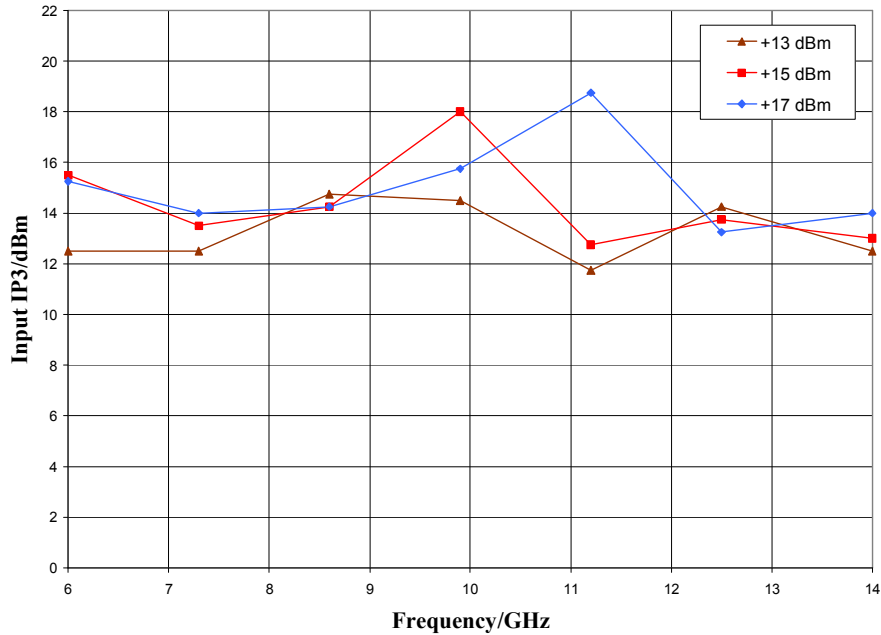
**Input IP3 vs. LO Drive, IF = 100 MHz**



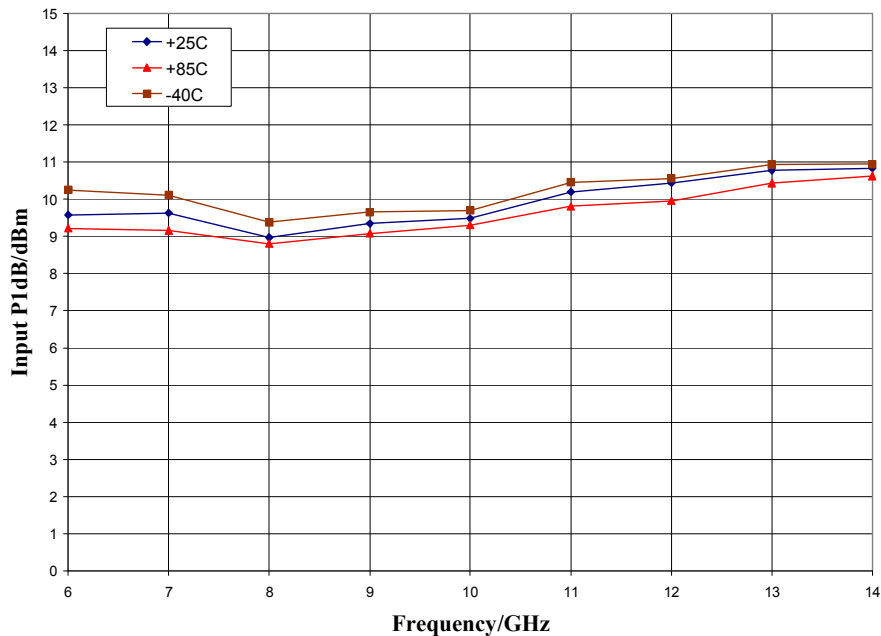
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### Typical Performance

**Upconverter Performance, Input IP3 vs. LO Drive, IF = 100 MHz**



**Input P1dB vs. Temperature, LO = +13 dBm, IF = 100 MHz USB**



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### Typical Performance

#### MxN Spurious Outputs

mRF	nLO				
	0	1	2	3	4
0	xx	6.5	33.5	30.5	29.5
1	17.5	0	37.5	38.5	57.5
2	>75	69.5	66.5	66.5	> 75
3	> 75	> 75	> 75	62.5	> 75
4	> 75	> 75	> 75	> 75	> 75

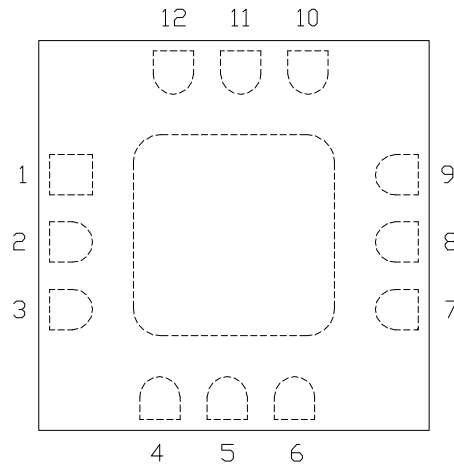
RF = 10.1 GHz @ -10 dBm  
 LO = 10.0 GHz @ +13 dBm  
 All values in dBc below the IF output power level (1RF - 1LO)




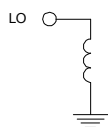
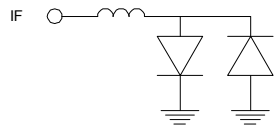
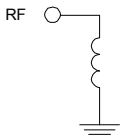


### Pin Description

#### Pin Diagram



#### Functional Description

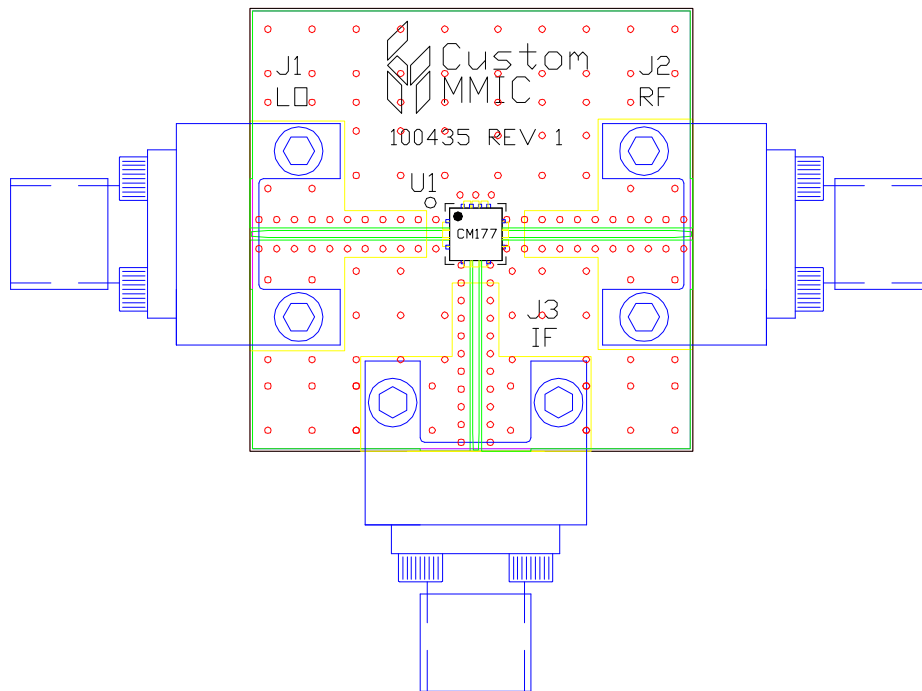
Pin	Function	Description	Schematic
1,3,4,6,7,9 and die paddle	Ground	Connect to RF / DC ground.	
2	LO	This pin is DC coupled and matched to 50 ohms.	
5	IF	This pin is DC coupled. For applications not requiring operation to DC, this port should be DC blocked externally using a series capacitor whose value has been chosen to pass the necessary IF frequency range. For operation to DC, this pin must not source or sink more than 16 mA of current or part non-function or part failure may result.	
8	RF	This pin is DC coupled and matched to 50 ohms.	
10-12	N/C	No connection required. These pins may be connected to RF/DC ground	

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### Applications Information

#### Evaluation Board

The circuit board shown has been developed for optimized assembly at Custom MMIC. A sufficient number of via holes should be used to connect the top and bottom ground planes. As surface mount processes vary, careful process development is recommended.



#### Bill of Material

Designator	Value	Description
J1 - J3		SMA End Launch Connector
U1		CMD177C3 Fundamental Mixer
PCB		100435 Evaluation PCB

**GaAs MMIC devices are susceptible to damage from Electrostatic Discharge. Proper precautions should be observed during handling, assembly and test.**

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